

Selective Inventory Exchange (SIEP)



CC-DEVPACK-DEBUG EVM Overheating

TI Part Number: CC-DEVPACK-DEBUG

Approval Date: 2016-01-17

Technology: EVM

Dear Customer,

Texas Instruments (“TI”) strives to comply with the strictest quality standards and processes to provide the highest quality products to TI customers. This letter serves to formally notify you that TI has identified an issue potentially affecting all versions of the CC-DEVPACK-DEBUG emulator board. This Evaluation Module (EVM) is subjected to TI’s **Selective Inventory Exchange Process (SIEP)**.

Texas Instruments appreciates your business and apologizes for any inconvenience this may cause. Please feel free to contact **TI Customer Service** or your field sales representative, if you need more information.

Issue Description and Technical Details

The CC-DEVPACK-DEBUG EVM (the “Debugger”) is used with TI’s second-generation CC2650STK SensorTag EVM.

TI has received reports that the CC-DEVPACK-DEBUG sometimes gets hot when connected with the CC2650STK while either EVM is powered. Depending on the usage mode and power-up process, the overheating may cause deformation of the black plastic on the CC2650STK. See Figure 1 for an example.



Figure 1: Black plastic on CC2650STK EVM

The CC-DEVPACK-DEBUG EVM hot spot location is surrounded by red borders in Figure 2.

Issue Symptoms and Isolation:

The overheating symptom may arise when plugging a USB cable into the standalone CC-DEVPACK-DEBUG or when connecting the CC-DEVPACK-DEBUG to the

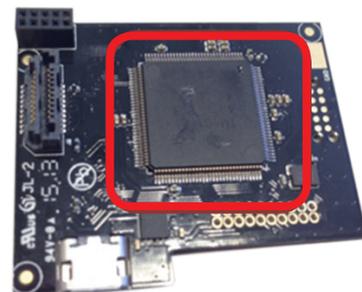


Figure 2: CC-DEVPACK-DEBUG EVM

CC2650STK while either EVM is powered. If you observe this device getting hot, you should immediately disconnect USB power and contact TI per the provided directions in the “Disposition” section of this document.

Risk Assessment and Mitigation Actions:

There is a potential for the TM4C microcontroller on the CC-DEVPACK-DEBUG EVM to overheat, depending on the usage mode and power-up method.

The overheating symptom is more likely to be observed when plugging a USB cable into a standalone CC-DEVPACK-DEBUG or when connecting the CC-DEVPACK-DEBUG to the CC2650STK while either EVM is powered.

The area identified in Figure 2 can have surface temperatures increase to levels that could potentially cause a burn hazard when touching this area. One possible indication of the CC-DEVPACK-DEBUG reaching elevated temperatures is a potential deforming of the black plastic on the connected CC2650STK as shown in Figure 1.

The appropriate connection procedure is as follows:

1. Insert battery into CC2650STK being mindful of the correct polarity (regardless of version)
2. Connect the unpowered CC-DEVPACK-DEBUG to the CC2650STK
3. Insert USB power to the CC-DEVPACK-DEBUG.

Material/Devices Affected (“Affected Material”):

All revisions of CC-DEVPACK-DEBUG:

- Revision 1.0
- Revision 1.1
- Revision 1.2

The revision number of your CC-DEVPACK-DEBUG is located in silk screen on the top-side of the debugger (as shown in Figure 3).

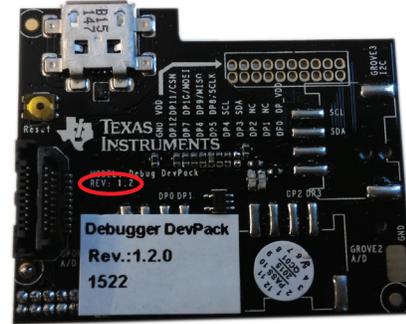


Figure 3: CC-DEVPACK-DEBUG board revision number.

Disposition:

Please immediately review your inventory against the TI Affected Material, and determine if you desire to discard the Affected Material and receive a replacement.

If you choose to ask TI for replacement, please contact TI Customer Service (<http://www.ti.com/general/docs/contact.tsp>) in your respective region or your dedicated Customer Service Representative that will provide information on how to get a new board shipped to your address as soon as they become available.

If you determine that the described issue does not affect your application development(s) and you do not wish to receive a replacement for the Affected Material, your decision represents your acknowledgement of the issue, your intention to utilize the Affected Material in your application development(s) despite possible issues, and your agreement that TI shall not be responsible for any issue(s) arising from your decision to use the Affected Material.

Thank you for your cooperation,

James L. Bender, P.E.
Director, Product Regulatory and Safety Compliance
Email: jbender@ti.com

Dag Grini
Customer Quality Engineer
Email: d.grini@ti.com

How to Identify the Material?

1) By Ship Track Code (STC)

The easiest and fastest way to identify the material is to compare the affected Ship Track Codes (STC) in the xls-file (column labeled as “**STC**”) with the Ship Track Codes (STC) of the material you have in stock.



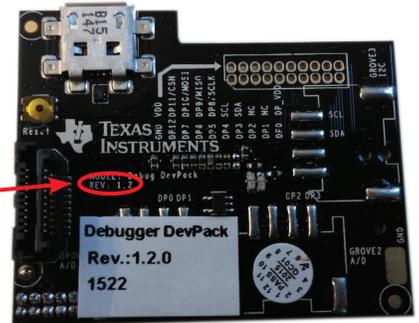
This is the Ship Track Code (STC) – the unique tracking number for each shipping container!

Left side of label	Center	Right side of label
MS LVL: Moisture sensitivity level SEAL DT: Seal date of the units FLR LIFE: Floor life TMP: Temperature	2D bar code label	(1P) TI part number (Q) Quantity within tape & reel (D) Datecode (YYWW = Year/Week) (31T) QA lot number incl. assembly site and lot # (1T) Ship track code (P) Customer part # (2P) Die revision of TI part number (V) Supplier (20L) Location of wafer fab (21L) Country of wafer fab (22L) Location of assembly site (23L) Country of assembly site

2) By PCB Revision

In case the material in question has already been removed out of the original TI carrier boxes, the identification of the material must be done by PCB revision printed on each board’s top surface. Please compare the board revision you have to revision 1.2, which is the latest affected revision of the CC-DEVPACK-DEBUG board.

This is the revision number



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